

# Korean International Semiconductor Conference & Exhibition on Manufacturing Technology 2025

# KISM 2025 BUSAN

Re:Innovation of Semiconductor Manufacturing for AI Ecosystem

[TuF2]	<b>Processin</b>	g for 3D	Integration
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Session Date November 11 (Tue.), 2025

**Session Time** 14:50-16:25

Session Room F (Panorama Room, 16F)

[TuF2-1] [Plenary] 14:50-15:35

#### Advanced Packaging Technology with Cu-Cu Hybrid Bonding

Takafumi (Tak) Fukushima (Tohoku Univ., Japan)

[TuF2-2] [Invited] 15:35-16:05

### Vertical Fan-Out (VFO) Technology for Memory and Storage Applications

Ji Yong Park (SK hynix Inc., Korea)

[TuF2-3] [Invited] 16:05-16:25

## **Enabling 3D Integration: Advances in Hybrid Wafer Bonding Technology**

Thomas Kasbauer (EV Group, Austria)